

AUG 13 2001

OMB No. 0651-0011

**INFORMATION
DISCLOSURE
STATEMENT**

Atty. Docket No.:

Serial No.:

56523US002

Unknown

Applicant(s):

Todd R. Williams, et al.

Filing Date:

May 31, 2001

Group:

Unknown

U.S. PATENT DOCUMENTS

| Examiner Initial | Document Number | Date | Name | Class | SubClass | Filing Date If Appropriate |
|------------------|-----------------|----------|------------------|-------|----------|----------------------------|
| WPF | 2,585,915 | 02-19-52 | Chavannes | 264 | 284 | |
| | 3,689,346 | 09-05-72 | Rowland | 156 | 245 | |
| | 4,191,451 | 03-04-80 | Hodges | 359 | 452 | |
| | 4,374,077 | 02-15-83 | Kerfeld | 264 | 1.33 | |
| | 4,414,316 | 11-08-83 | Conley | 430 | 496 | |
| | 4,576,850 | 03-18-86 | Martens | 428 | 156 | |
| | 4,582,885 | 04-15-86 | Barber | 528 | 28 | |
| | 4,668,558 | 05-26-87 | Barber | 428 | 156 | |
| | 4,810,435 | 03-07-89 | Kamada, et al. | 264 | 495 | |
| | 4,920,038 | 04-24-90 | Budde, et al. | 430 | 315 | |
| | 5,175,030 | 12-29-92 | Lu, et al. | 428 | 30 | |
| | 5,183,597 | 02-02-93 | Lu | 264 | 1.58 | |
| | 5,260,175 | 11-09-93 | Kowanz, et al. | 430 | 326 | |
| | 5,330,799 | 07-19-94 | Sandor, et al. | 427 | 510 | |
| | 5,468,542 | 11-21-95 | Crouch | 428 | 215 | |
| | 5,754,332 | 05-19-98 | Crowley | 359 | 296 | |
| | 5,815,306 | 09-29-98 | Sheridon, et al. | 359 | 296 | |
| | 5,847,327 | 12-08-98 | Fischer, et al. | 174 | 258 | |

FOREIGN PATENT DOCUMENTS

| | Document Number | Date | Country | Class | SubClass | Translation | |
|-----|-----------------|----------|---------|-------|----------|-------------|----|
| | | | | | | Yes | No |
| WPF | EP 0 130 659 A1 | 01-09-85 | Europe | — | — | | |
| | EP 0 228 671 A1 | 07-15-87 | Europe | — | — | | |
| | WO 90/15673 | 12-27-90 | PCT | — | — | | |
| | WO 98/21626 | 05-22-98 | PCT | — | — | | |
| | WO 00/73083 A1 | 12-07-00 | PCT | — | — | | |
| | WO 0/00563A1 | 01-06-00 | PCT | — | — | | |

OTHER DOCUMENTS (Including Authors, Title, Date, Pertinent Papers, etc.)

| | |
|-----|---|
| WPF | Darren Hitchcock, "Microvias, High Speed, and Flex," Proc. IPC Natl. Conf. on Flexible Circuits, 19-20 May 1997 (Phoenix, AZ). |
| | Charles Lassen, "Build-Up Multilayers," Printed Circuit Fabrication 20 (6), June 1997, pp. 22-24. |
| | Charles E. Bauer, "Using Chip Scale Packages," Advanced Packaging 5 (4), July/August 1996, pp. 8-10. |
| | Howard Green and Phillip Garrou, "Introduction to Large Area Substrate Processing," Advancing Microelectronics 24 (2), March/April 1997, pp. 10-15. |

EXAMINER

William Phillip Fletcher III
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Date Considered

12/18/02

*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.